AMENDMENTS TO THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) A thin film forming apparatus to form a thin film on each of a plurality of substrates held on an outer circumferential surface of a cylindrical substrate holder that is rotatable about a rotating shaft, while the substrate holder is being rotated in an evacuatable chamber, the thin film forming apparatus comprising:

a transferring device that transfers one of a substrate itself or a substrate fixing jig fixedly holding a substrate or a plurality of substrates that is removeably securable onto the outer circumferential surface of the substrate holder to/from the substrate holder in the evacuatable chamber; and

means for releasably securing the substrate itself or the substrate fixing jig transferred by the transferring device onto the outer circumferential surface of the substrate holder,

wherein the cylindrical substrate holder is rotatable around the rotating shaft which is provided in a horizontal direction;

wherein the transferring device is provided outside the evacuatable chamber and includes an arm insertable into a gap between the substrate holder and the substrate fixing jig or the substrate itself;

wherein the arm, when holding the substrate fixing jig or the substrate itself, is transferred along the outer circumferential surface of the cylindrical substrate holder in a direction parallel with the rotating shaft; and

wherein an end of one of the substrate fixing jig or the substrate itself, which is transferable by the transferring device, is fixable to the cylindrical substrate holder by the means for releasably securing.

2. (Previously Presented) The thin film forming apparatus according to claim 1, wherein the substrate holder is installed rotatably about a horizontal rotating shaft, and the transferring device transfers one of the substrate fixing jig and the substrate itself in a horizontal direction.

3. (Previously Presented) The thin film forming apparatus according to claim 1, wherein the transferring device transfers one of the substrate fixing jig and the substrate itself in an axial direction of the rotating shaft.

4. (Previously Presented) The thin film forming apparatus according to claim 1, wherein the transferring device transfers one of the substrate fixing jig and the substrate itself in a direction parallel to an outer circumferential surface of the substrate holder.

5. (Previously Presented) The thin film forming apparatus according to claim 1, wherein both the transferring to/from action by the transferring device and the securing action by the means for releasably securing are performed in a depressurized environment.

6. (Previously Presented) The thin film forming apparatus according to claim 1, wherein the releasing action by the means for releasably securing is controlled by an electrical signal.

7. (Previously Presented) The thin film forming apparatus according to claim 1, wherein the means for releasably securing has a mechanism to hold one of the substrate fixing jig and the substrate itself by pressing with a retaining member, and a mechanism to release one of the substrate fixing jig and the substrate itself from the holding by compressing the retaining member by one of a drive unit mounted outside of the evacuatable chamber or a drive unit mounted inside of the substrate holder.

8. (Previously Presented) The thin film forming apparatus according to claim 1, wherein the means for releasably securing secures the substrate fixing jig by magnetic force.

9. (Previously Presented) The thin film forming apparatus according to claim 1, wherein the transferring device is installed in a transferring chamber which is connected to the evacuatable chamber via a valve, and the transferring chamber is evacuatable.

10. (Previously Presented) The thin film forming apparatus according to claim 9, further comprising a load/unload chamber which is connected to the transferring chamber via a valve, and the load/unload chamber is evacuatable.

11. (Previously Presented) The thin film forming apparatus according to claim 1, wherein the film is formed by one of sputtering, deposition, and CVD, or a combination thereof.

12. (Previously Presented) The thin film forming apparatus according to claim 1, wherein one of a reaction gas supplying device to supply a reaction gas, a plasma exposing device to expose plasma, a ion irradiating device to irradiate ions, and an etching device to etch a portion of the thin film, or a combination thereof is applicable to the thin film.

13. (Previously Presented) The thin film forming apparatus according to claim 1, wherein the substrate fixing jig comprises outwardly bent end parts, the outwardly bent end parts defining a middle substrate fixing portion for receiving the substrate and defining a gap between the substrate holder and the substrate fixing jig when the substrate fixing jig is mounted to the substrate holder.

14 (Previously Presented) The thin film forming apparatus according to claim 1, wherein the means for releasably securing comprises an upper securing member and a lower securing member configured to receive an end part of the substrate fixing jig.

15. (Previously Presented) The thin film forming apparatus according to claim 13, wherein the means for releasably securing comprises a moveable shaft, and a retaining member biasing the moveable shaft.

16. (Previously Presented) The thin film forming apparatus according to claim 15, wherein the means for releasably securing comprises a hold-down plate fixedly attached to an upper end of the moveable shaft.